

## NOTES (UNLESS OTHERWISE SPECIFIED):

### **GENERAL**

- 1) PCB IS 12-LAYER, .062" THICK,
- 2) CONSTRUCTION IS SOLDER-MASK-OVER-BARE-COPPER (SMOBC).
- 3) ACCEPTABILITY SHALL BE BASED ON PC-A-600, CLASS 2.
  4) THE FOLLOWING GERBER RS274X PHOTO TOOL FILES SHALL BE USED TO DEFINE ALL CIRCUIT FEATURES: \*.GTL - TOP LAYER GERBER DATA
- \*.GP1 INTERNAL PLANE LAYER 1 GERBER DATA
- \*.G1 MID LAYER 1 GERBER DATA
- \*.GP2 INTERNAL PLANE LAYER 2 GERBER DATA
- \*.GP3 INTERNAL PLANE LAYER 3 GERBER DATA \*.GP4- INTERNAL PLANE LAYER 4 GERBER DATA
- \*.GP5- INTERNAL PLANE LAYER 5 GERBER DATA
- \*.GP6- INTERNAL PLANE LAYER 6 GERBER DATA
- \*.GP7- INTERNAL PLANE LAYER 7 GERBER DATA
- \*.GP8- INTERNAL PLANE LAYER 8 GERBER DATA \*.GP9- INTERNAL PLANE LAYER 9 GERBER DATA
- \*.GBL BOTTOM LAYER GERBER DATA
- \*.GTO TOP OVERLAY GERBER DATA
- \*GBO -- BOTTOM OVERLAY GERBER DATA
- \*.GTP TOP-SDE SOLDER PASTE MASK
- \*.GTS TOP SOLDER MASK GERBER DATA \*,GBS - BOTTOM SOLDER MASK GERBER DATA
- 5) THE PHOTO TOOL SHALL NOT BE COMPENSATED WITHOUT PRIOR ENGINEERING APPROVAL PCB DESIGNER: RICH LOBDILL PH (805) 880-1621 FAX (805) 961-1792.

#### FABRICATION TOLERANCES

- 6) END PRODUCT CONDUCTOR WIDTHS AND PAD DIAMETERS SHALL NOT VARY MORE THAN 0.002" FROM THE 1:1 DIMENSIONS OF THE MASTER ARTWORK.
- 7) THE CONDUCTIVE PATTERN SHALL BE POSITIONED SO THAT THE LOCATION OF ANY PAD OR LAND SHALL BE WITHIN 0.005" DIAMETER TO THE TRUE POSITION OF THE HOLE IT CIRCUMSCRIBES. 8.1) DRILL TOLERANCES +/- 0.003"

  8.2) ALL DRILL HOLE SIZES AND TOLERANCES APPLY AFTER PLATING.
- 9) THE MINIMUM ANNULAR RING SHALL BE 0.005".
- 10) BOW AND TWIST SHALL NOT EXCEED 0.010" PER INCH.
- 11) FOR PCB ROUTING DIMENSIONS: .XXX =  $\pm$ /-.005" .XX =  $\pm$ /-.020"

### MATERIAL

- 12) BASE MATERIAL IS FR4 EPOXY FIBERGLASS
- 13) SEE STACK-UP LEGEND FOR COPPER CLADDING CALL OUTS

## PLATING

- 14) ALL HOLES AND CONDUCTIVE SURFACES SHALL BE PLATED WITH A MINIMUM OF 0.001" COPPER.
- 15) AFTER SOLDERMASK, ALL EXPOSED HOLES AND CONDUCTIVE SURFACES SHALL BE COATED WITH A GOLD IMMERSION PLATING TO PRESERVE SOLDERABILITY.

- 16) THE SOLDERMASK SHALL BE BLACK LIQUID PHOTO-MAGEABLE PER PC-SM-840, TYPE-B, CLASS 2.
- 17) THE SOLDERMASK REGISTRATION ALLOWANCE IS 0.003". THERE SHALL BE NO SOLDERMASK ON ANY SOLDER PAD OR LAND.

- 18) THE LEGEND SHALL BE SCREEN-PRINTED USING PERMANENT YELLOW EPOXY INK.
  19) THE SCREEN PRINTING REGISTRATION ALLOWANCE IS 0.007". THERE SHALL BE NO NK ON ANY
- SOLDER PAD OR LAND.
- 20) THE VENDOR CODE AND UL FLAMMABILITY RATING MAY BE ETCHED IN THE FOIL OR MARKED IN PERMANENT EPOXY INK (VENDOR'S OPTION).

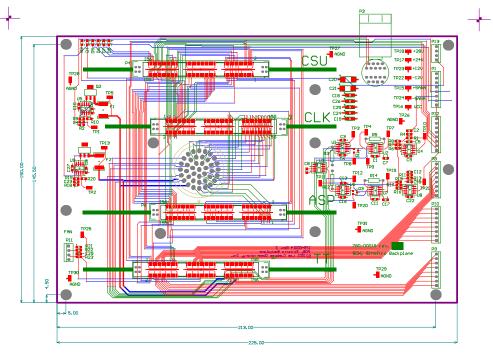
# ELECTRICAL TESTING

21) ALL BOARDS SHALL BE ELECTRICALLY TESTED TO THE SUPPLED PC-D-356A NET LIST FOR CONTINUITY, OPENS AND SHORTS.

Layer Name	Copper cladding
Top Layer (*.GTL)	1/2 oz. (1 oz. Finished)
AGND (*.GP1)	1/2 oz
Mid-Layer 1 (*.G1)	1/2 oz
GND (*.GP2)	1/2 oz
+12V (*.GP3)	1/2 oz
-12V (*.GP4)	1/2 oz
+5ANA (*.GP5)	1/2 oz
-5ANA (*.GP6)	1/2 oz
+28V (*.GP7)	1/2 oz
VCC (*.GP8)	1/2 oz
+24V (*.GP9)	1/2 oz

NOTICE

THIS DRAWNG EMBODES A PROPRETARY DESIGN OWNED BY LAS CUMBRES OBSERVATORY, IT IS SUBMITTED FOR A SPECPIC PURPOSE UNDER A CONFIDENTIAL RELATIONARY, AND EXCEPT FOR PURPOSES EMPRESSLY GRANTED IN METRICA, LIR GOITS ARE RESERVED BY LAS CUMBRES OBSERVATORY.



175-00014 REV 2, SINISTRO BACKPLANE LAS CUMBRES OBSERVATORY

\*.GTO--MEOPROMERLAY/COVERSUS/DIA/TA/TA

PRIMARY PCB SPECIFICATIONS (REFER TO COMPLETE SPEC LISTING AT LEFT FOR FURTHER DETAILS) NUMBER OF LAYERS -12

FINISHED THICKNESS .062" BASE MATERIAL FR4

GOLD IMMERSION PLATING TYPE SOLDER MASK COLOR -**BLACK** 

Las Cumbres Observatory, Inc. Las Cumbres Observator 6740 Cortona Dr. Goleta, CA 93117 www.lcogt.net 6/28/2011 Rich Lobdill 175-00014, Sinistro Backplane - GPT <sup>\*</sup> 1 ∘ 20